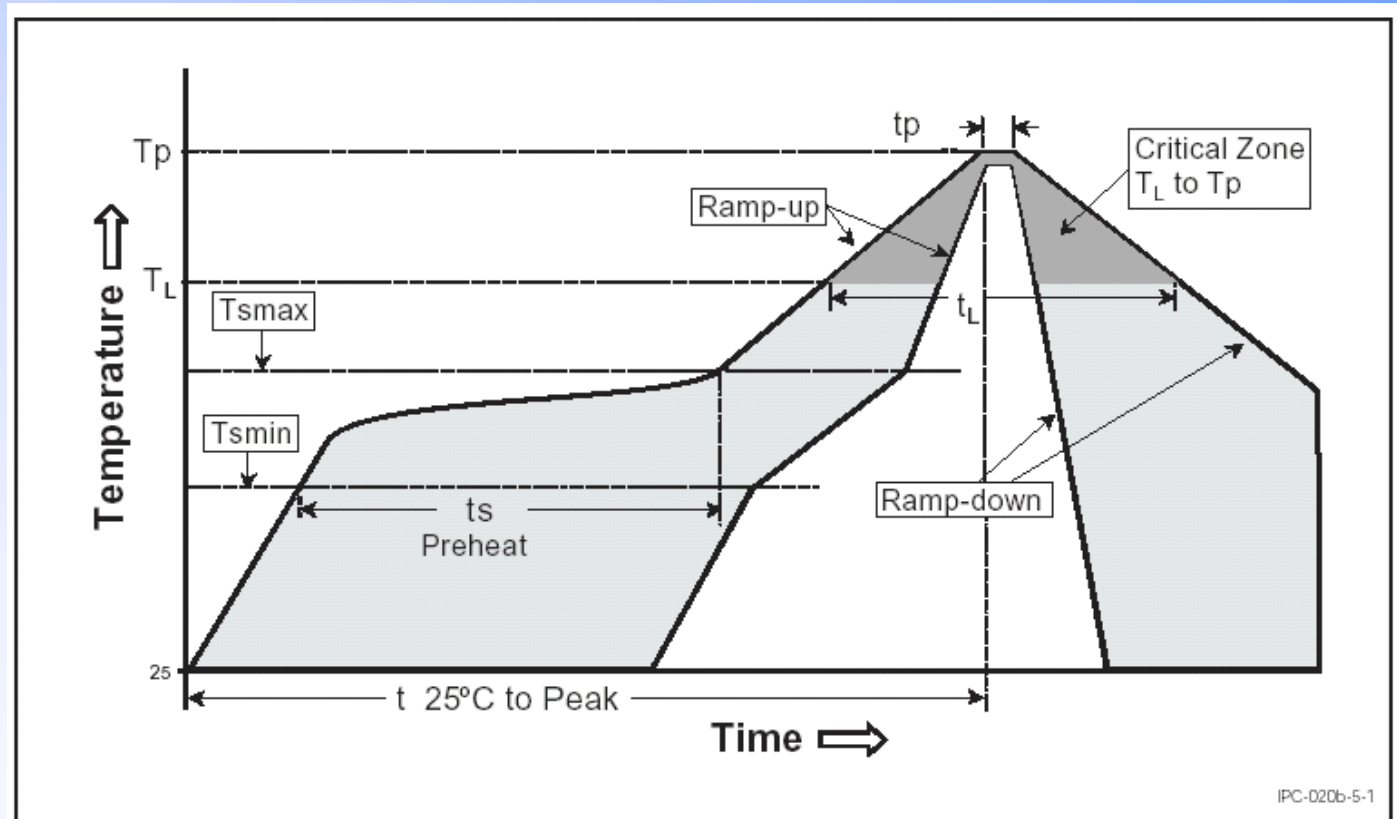


Recommend Reflow Profile

PCBA reflow profile depends on the thermal mass of the entire populated board. The actual temperature used in the reflow oven is a function of:

- Solder paste types
- Board density
- Component location
- Component mass
- Board finish



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_{smax} to T_p)	2°C/second max	2°C/second max
Preheat		
-Temperature Min (T_{smin})	100°C	150°C
-Temperature Max (T_{smax})	150°C	200°C
-Time (min to max) (ts)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T_L)	183°C	217°C
-Time (t_L)	60-150 seconds	60-150 seconds
Peak Temperature (T_p)	225+0/-5°C	245+5/-5°C
Time within 5°C of actual Peak Temperature (t_p)	20 seconds max	30 seconds max
Ramp-down Rate	3°C/second max.	3°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Note:

- 1.All temperatures refer to topside of the package, measured on the package body surface.
- 2.Actual board assembly depends on other parts on board density and follower solder paste manufacturers's guideline.